

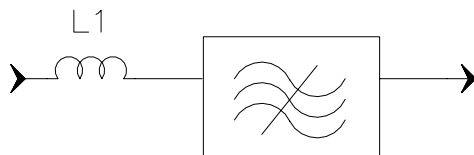
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	69.8	70	70.2
Insertion Loss	dB	-	23.3	26
1 dB Bandwidth	MHz	17.6	17.9	-
3 dB Bandwidth	MHz	18	19.1	-
40 dB Bandwidth	MHz	-	23.3	23.5
50 dB Bandwidth	MHz	-	23.8	-
Passband Variation	dB	-	0.5	0.6
Absolute Delay	usec	-	1.54	-
Phase Linearity($f_0 \pm 8\text{MHz}$)	deg	-	4	-
Group Delay Variation($f_0 \pm 8\text{MHz}$)	nsec	-	40	60
Ultimate Rejection	dB	50	58	-
Material Temperature coefficient	KHz/°C	-5.74		
Ambient Temperature	°C	25		
Package Size	DIP2212 (22.2x12.8x4.7mm3)			

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

Matching Configuration



L1=270nH
Source/Load Impedance=50 ohm

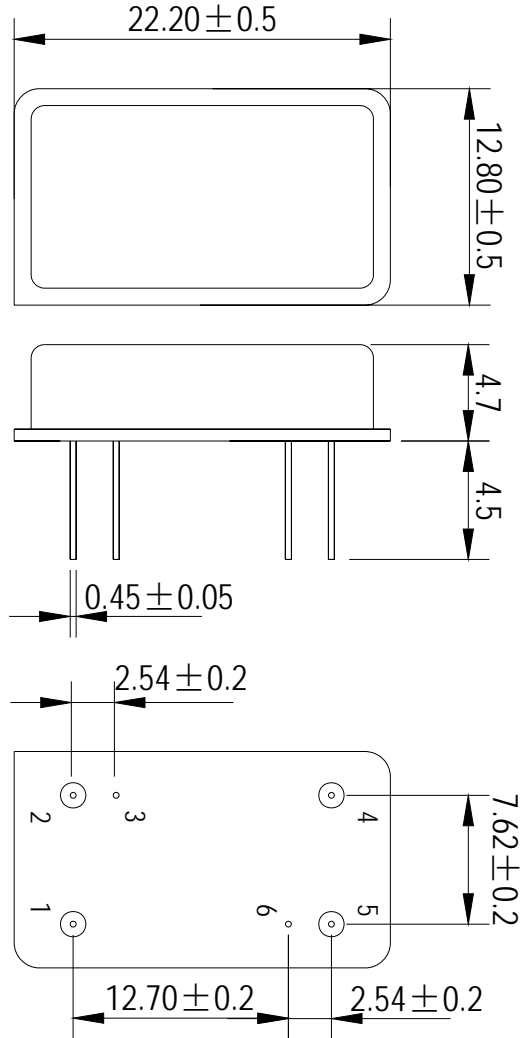
Notes - Component values may change depending on board layout.



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Part Number	LBN7012		
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Package Dimension



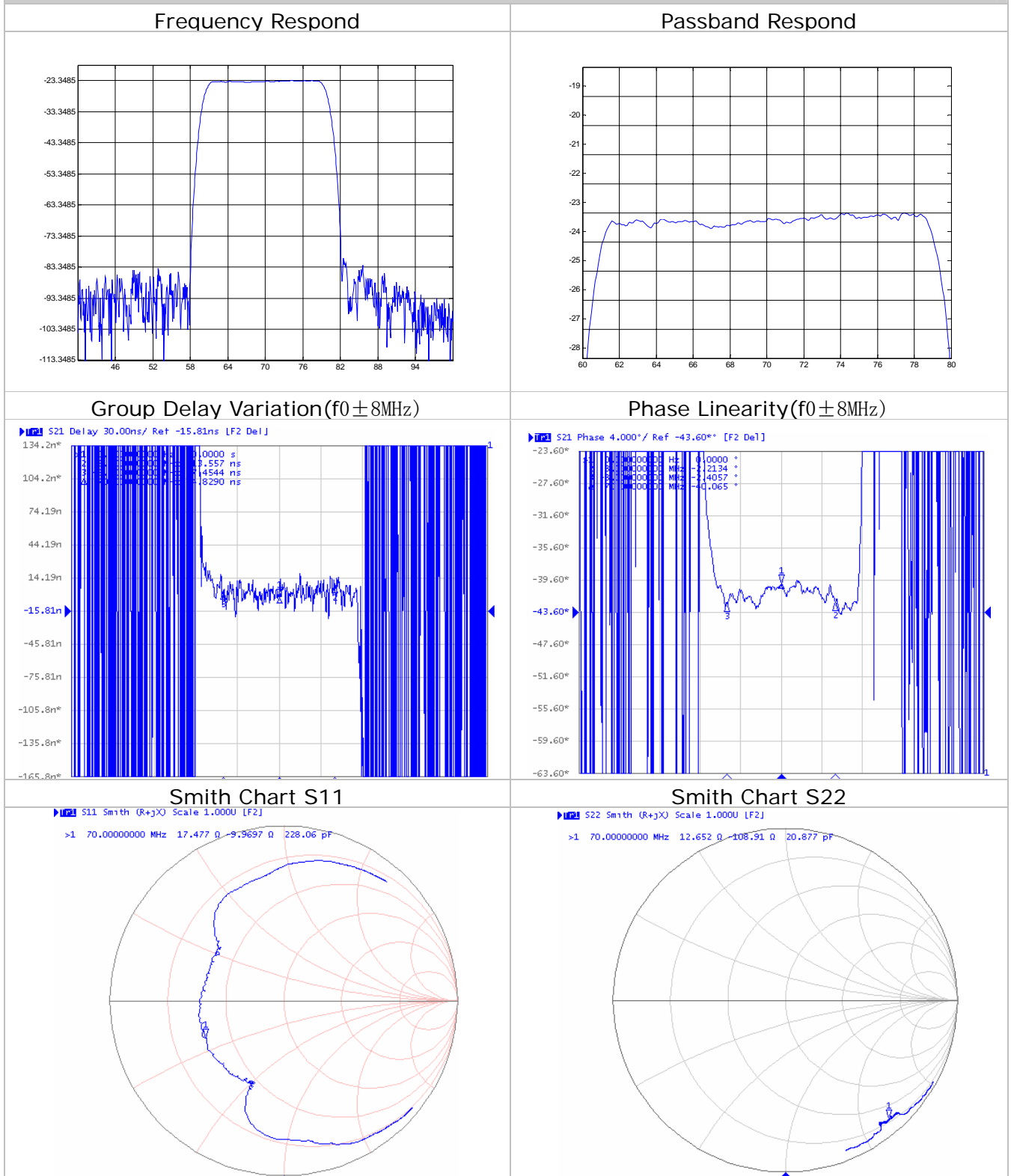
Input: 1
Output: 5



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Typical Performance



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